Power MOSFET

30 Amps, 60 Volts Single N-Channel DPAK

Features

- Low R_{DS(on)}
- High Current Capability
- Avalanche Energy Specified
- These are Pb-Free Devices

Applications

- LED Lighting and LED Backlight Drivers
- DC-DC Converters
- DC Motor Drivers
- Switch Mode Power Supplies
- Power Supplies Secondary Side Synchronous Rectification

MAXIMUM RATINGS (T_J = 25°C Unless otherwise specified)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	60	V
Gate-to-Source Voltage - Continuous			V _{GS}	±20	V
Gate-to-Source Voltage - Nonrepetitive (T _P < 10 µs)			V _{GS}	±30	V
Continuous Drain	Steady State	T _C = 25°C	I _D	30	Α
Current R _{θJC} (Note 1)	State	T _C = 100°C		23	
Power Dissipation $R_{\theta JC}$ (Note 1)	Steady State	T _C = 25°C	P _D	68	W
Pulsed Drain Current	t _p = 10 μs		I _{DM}	84	Α
Operating and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			IS	30	Α
Single Pulse Drain-to-Source Avalanche Energy – Starting $T_J = 25^{\circ}C$ ($V_{DD} = 50 \ V_{dc}, \ V_{GS} = 10 \ V, \ I_{L(pk)} = 30 \ A,$ L = 0.3 mH, $R_G = 25 \ \Omega$)			E _{AS}	135	mJ
Lead Temperature for Soldering Purposes, 1/8" from Case for 10 Seconds		TL	260	°C	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case (Drain) Steady State	$R_{\theta JC}$	2.2	°C/W
(Note 1)	$R_{\theta,JA}$	58.5	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 Surface mounted on FR4 board using 1 sq in pad size, (Cu Area 1.127 sq in [1 oz] including traces).

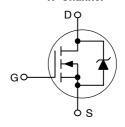


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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX (Note 1)
60 V	26 mΩ @ 10 V	30 A

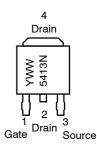
N-Channel



MARKING DIAGRAM



DPAK CASE 369AA STYLE 2



5413N = Device Code

Y = Year WW = Work Week G = Pb-Free Device

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C Unless otherwise specified)

Characteristics	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				•		•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				67.5		mV/°C
Zero Gate Voltage Drain Current	I_{DSS} $V_{GS} = 0 \text{ V}$ $T_{J} = 25^{\circ}\text{C}$				1.0	μΑ	
		V _{DS} = 60 V	T _J = 150°C			50	
Gate-Body Leakage Current	I _{GSS}	V _{DS} = 0 V, \	/ _{GS} = ±20 V			±100	nA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}$	I _D = 250 μA	2.0	3.4	4.0	V
Negative Threshold Temperature Coefficient	V _{GS(th)} /T _J				7.9		mV/°C
Drain-to-Source On-Voltage	V _{DS(on)}	V _{GS} = 10 \	V, I _D = 20 A		0.37	0.52	V
		V _{GS} = 10 V, I _D	₀ = 20 A, 150°C		0.86		
Drain-to-Source On-Resistance	R _{DS(on)}	V _{GS} = 10 \	V, I _D = 20 A		18.5	26	mΩ
Forward Transconductance	9FS	V _{DS} = 15 \	V, I _D = 20 A		36		S
CHARGES, CAPACITANCES & GATE RESIST	ANCE			•			•
Input Capacitance	C _{iss}	V _{DS} = 25 V	, V _{GS} = 0 V,		1160	1725	pF
Output Capacitance	C _{oss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz			240		
Transfer Capacitance	C _{rss}				100		1
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 10 \text{ V}, V_{DS} = 48 \text{ V},$ $I_{D} = 20 \text{ A}$			35	46	nC
Threshold Gate Charge	Q _{G(TH)}				1.4		1
Gate-to-Source Charge	Q _{GS}				6.5		
Gate-to-Drain Charge	Q_{GD}				16.1		
SWITCHING CHARACTERISTICS, V _{GS} = 10 V	(Note 3)				•		•
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10 V,	V _{DD} = 48 V,		11		ns
Rise Time	t _r	$I_{D} = 20 A,$	$R_G = 2.5 \Omega$		20		1
Turn-Off Delay Time	t _{d(off)}				28		1
Fall Time	t _f				8.0		1
DRAIN-SOURCE DIODE CHARACTERISTICS	<u> </u>			I	1	1	
Forward Diode Voltage (Note 2)	V_{SD}	V _{GS} = 0 V	T _J = 25°C		0.87	1.2	V
		I _S = 20 A	T _J = 125°C		0.8		1
Reverse Recovery Time	t _{rr}	$I_S = 20 A_{dc}$	$V_{GS} = 0 V_{dc}$		52		ns
Charge Time	ta	dl _S /dt = 100 A/μs			37		1
Discharge Time	t _b				15		1
Reverse Recovery Stored Charge	Q _{RR}				105.7		nC

ORDERING INFORMATION

Device	Package	Shipping [†]
NTD5413NT4G	DPAK (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES

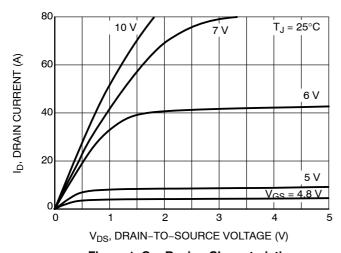


Figure 1. On-Region Characteristics

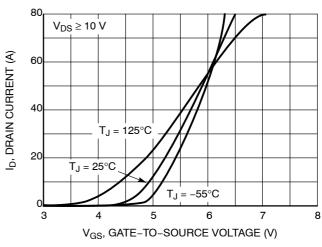


Figure 2. Transfer Characteristics

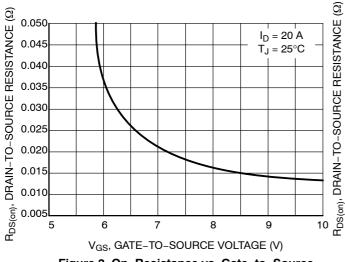


Figure 3. On-Resistance vs. Gate-to-Source Voltage

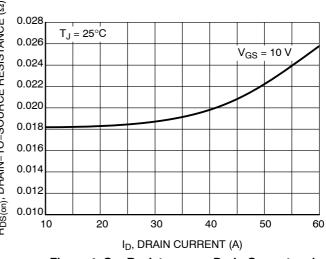


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

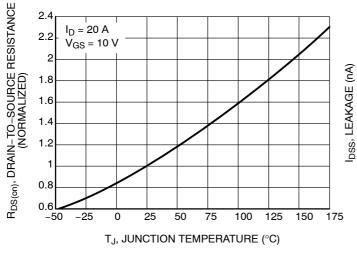


Figure 5. On–Resistance Variation with Temperature

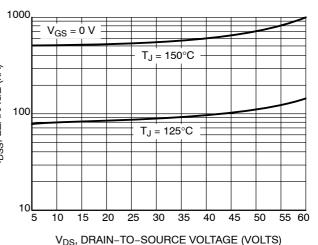


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL PERFORMANCE CURVES

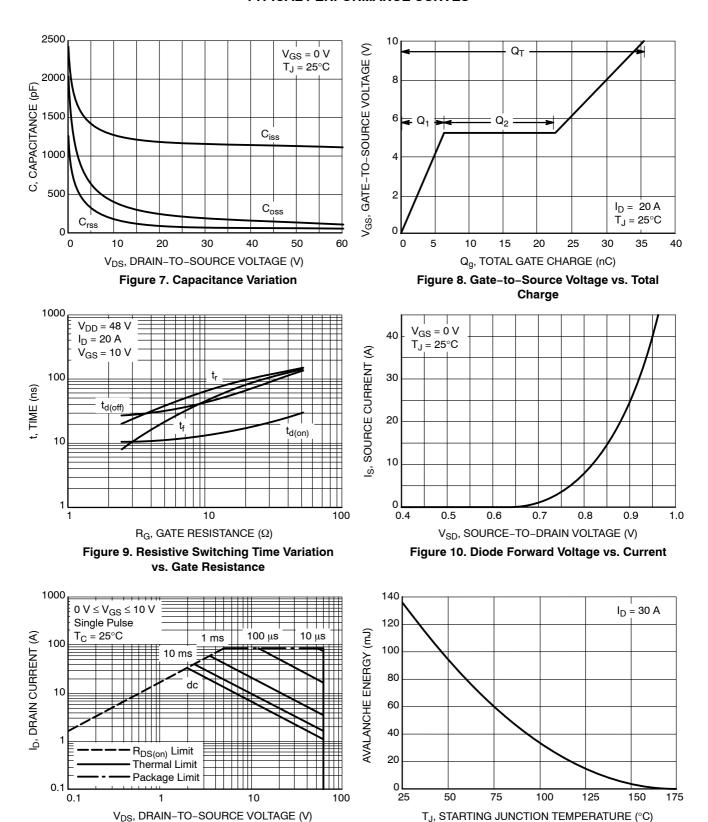


Figure 11. Maximum Rated Forward Biased Safe Operating Area

Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

TYPICAL PERFORMANCE CURVES

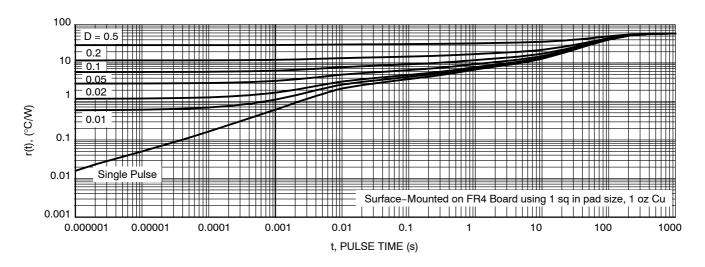
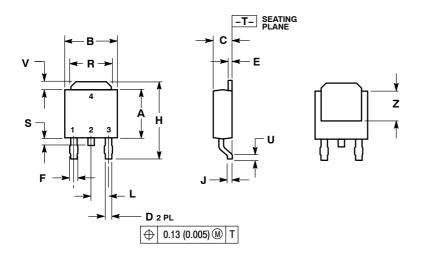


Figure 13. Thermal Response

PACKAGE DIMENSIONS

DPAK CASE 369AA-01 **ISSUE A**



NOTES:

- 1. DIMENSIONING AND TOLERANCING
- PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

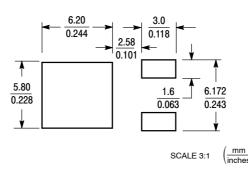
	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.22
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.025	0.035	0.63	0.89
E	0.018	0.024	0.46	0.61
F	0.030	0.045	0.77	1.14
Н	0.386	0.410	9.80	10.40
J	0.018	0.023	0.46	0.58
L	0.090	BSC	2.29	BSC
R	0.180	0.215	4.57	5.45
S	0.024	0.040	0.60	1.01
U	0.020		0.51	
V	0.035	0.050	0.89	1.27
Z	0.155		3.93	

STYLE 2:

PIN 1. GATE 2. DRAIN

- 3. SOURCE DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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